IN THE CLAIMS:

- (Currently Amended) A semiconductor substrate for a micro-fluid ejecting device, the substrate comprising:
 - a plurality of fluid ejection devices disposed on the substrate;
 - a plurality of driver <u>devices</u> transistors disposed on the substrate for driving the plurality of fluid ejection devices; and
 - a nonvolatile programmable memory matrix containing embedded programmable memory devices, the matrix being capable of being operatively connected to the micro-fluid ejecting device for collecting and storing information on the semiconductor substrate for operation of the micro-fluid ejecting device.
- (Currently Amended) The semiconductor substrate of claim 1 wherein the embedded programmable memory devices comprise transistors selected from the group consisting of PMOS and NMOS floating gate transistors.
- (Currently Amended) The semiconductor substrate of claim 1 wherein the embedded programmable memory devices have a memory density of greater than about 200 bits per square millimeter.
- 4. (Currently Amended) The semiconductor substrate of claim 1 wherein the programmable memory matrix comprises floating gate transistors.
- (Currently Amended) The semiconductor substrate of claim 1 wherein the programmable memory matrix comprises more than 128 memory devices.
- 6. (Currently Amended) The semiconductor substrate of claim 1 wherein the embedded programmable memory devices are programmable by applying a voltage of greater than about 8 volts for at least about 100 microseconds.
- (Currently Amended) The semiconductor substrate of claim 1 wherein the embedded programmable memory devices will pass from about 10 to about 200 microamps of

current at about 2 volts in a programmed state.

- 8. (Currently Amended) The semiconductor substrate of claim 1 wherein the embedded programmable memory devices will pass less than 3 microamps of current at about 2 volts in an unprogrammed state.
- 9. (Currently Amended) The semiconductor substrate of claim 1 wherein the memory matrix is erasable by ultraviolet light and further comprising a layer disposed adjacent the programmable memory matrix, said layer having properties sufficient to block ultraviolet light having a wavelength below about 400 nanometers.
- (Original)A printhead for an ink jet printer containing the semiconductor substrate of claim 9.
- 11. (Original) The printhead of claim 10 wherein the layer comprises a material selected from the group consisting of a photoresist material, and a metal layer, said layer having ultraviolet light blocking properties.
- 12. (Original) The printhead of claim 10 wherein the layer comprises a polyimide nozzle plate.
- 13. (Currently Amended) An ink jet printer cartridge for an ink jet printer comprising: a cartridge body having an ink supply source and a printhead attached to the cartridge body in fluid communication with the ink supply source, the printhead comprising:
 - a semiconductor substrate having a plurality of ink ejection devices disposed on the substrate;
 - a plurality of driver <u>devices</u> transistors disposed on the substrate for driving the plurality of ink ejection devices;
 - a <u>nonvolatile</u> programmable memory matrix containing embedded programmable memory devices, the matrix being operatively connected to <u>the</u> ink jet printer for collecting and storing

information on the semiconductor substrate for operation of the printer; and

- a nozzle plate attached to the semiconductor substrate for ejecting ink therefrom upon activation of the ink ejection devices.
- 14. (Original) The ink jet printer cartridge of claim 13 wherein the embedded programmable memory devices comprise transistors selected from the group consisting of PMOS and NMOS floating gate transistors.
- 15. (Original) The ink jet printer cartridge of claim 13 wherein the embedded programmable memory devices have a memory density of greater than about 200 bits per square millimeter.
- 16. (Original) The ink jet printer cartridge of claim 13 wherein the programmable memory matrix comprises floating gate transistors.
- 17. (Original) The ink jet printer cartridge of claim 13 wherein the programmable memory matrix comprises more than 128 memory devices.
- 18. (Original) The ink jet printer cartridge of claim 13 wherein the embedded programmable memory devices are programmable by applying a voltage of greater than about 8 volts for at least about 100 microseconds.
- 19. (Original) The ink jet printer cartridge of claim 13 wherein the embedded programmable memory devices will pass from about 10 to about 200 microamps of current at about 2 volts in a programmed state.
- 20. (Original) The ink jet printer cartridge of claim 13 wherein the embedded programmable memory devices will pass less than 3 microamps of current at about 2 volts in an unprogrammed state.
- 21. (Currently Amended) The ink jet printer cartridge of claim 13 wherein the memory matrix is erasable by ultraviolet light and further comprising a photoresist layer disposed

- adjacent the programmable memory matrix, said photoresist layer having properties sufficient to block ultraviolet light having a wavelength below about 400 nanometers.
- 22. (Currently Amended) The ink jet printer cartridge of claim 13 wherein the memory matrix is erasable by ultraviolet light and the nozzle plate comprises a polyimide nozzle plate having properties sufficient to block ultraviolet light having a wavelength below about 400 nanometers.
- 23. (New) A printhead for a micro-fluid ejecting device, the printhead comprising: a plurality of fluid ejection devices;
 - a plurality of driver devices for driving the plurality of fluid ejection devices; and
 - a nonvolatile programmable memory matrix containing embedded programmable memory devices, the matrix being capable of being operatively connected to a micro-fluid ejecting device for storing information for operation of the micro-fluid ejecting device.
- 24. (New) The printhead of claim 23, further comprising a controller wherein at least a portion of the matrix is readable by the controller.
- 25. (New) The printhead of claim 24, further comprising a controller wherein the at least a portion of the matrix is directly readable by the controller.
- 26. (New) The printhead of claim 23, wherein the programmable memory devices are embedded in a semiconductor.
- 27. (New) The printhead of claim 26, wherein the semiconductor comprises silicon.
- 28. (New) The printhead of claim 23, wherein the driver devices comprise transistors.